

Amendments to the Specification:

Please replace the paragraph beginning at page 3, line 18, with the following rewritten paragraph:

It is to be explicitly noted here that the applicant has filed ~~two other~~ another application[[s]] relating to a method[[s]] and apparatus[[es]] for processing a workpiece with a laser at a date very close to the application ~~day~~ date of the present patent application, namely ~~the applications no. ... ("Patching") and no. ... ("Trennmittel")~~ U.S. Serial No. 09/806,353, filed May 18, 2001. Herein and if required below in the following text, said application[[s]] ~~are~~ is explicitly referred to.

Please replace the paragraph beginning at page 5, line 18, with the following rewritten paragraph:

FIG. 2 schematically shows a functional block diagram of the construction of the controller 17. N signal input lines 18a and m signal output lines 18b are provided. They pass driver/coupling/converter/processing components 67a, 67b which carry out conversions related to data formats, performance and the likes. The controller 17 comprises at least one memory 64 in which different kinds of data can be stored. In addition, different general control or automatic control functions 65 are provided (for example for laser scanning, laser beam guidance, etc.). 68 denoted functions corresponding to the functions and features described in ~~the two other patent applications ("Patching" and "Trennmittel")~~ U.S. Serial No.

09/806,353 mentioned above. They may be provided together with the functions according to the invention and may have advantageous effects. 66 denotes a channel enabling the required communication between the individual ones. As far as it is to be regarded as hardware it may, for example, be a bus of a computer.

Please replace the paragraph beginning at page 8, line 22 through page 9, line 4, with the following rewritten paragraph:

FIG. 5 shows a function for continuously storing the continuously measured depth data z . The storage is preferably carried out in memory locations corresponding to the position of the measured location in the working area of the device. It is not always possible to produce the current bottom 112 so evenly as shown in [[Fir. 7]] FIG. 7. Rather, waviness or plateaux or indentations may occur. In FIG. 6 the numeral 103 denotes a plateau. Under consideration the movement of the laser beam 12 in FIG. 7 in the direction of the arrow 111 a feeding speed v_x may be determined. If, on the other hand, it is assumed that the reaction speed of the system is limited to one measurement, a time t_R can be determined as a reaction period which will pass until a measured value of z can have an effect on the laser 12. Due to the reaction time t_R and the feeding speed v_x control interventions will principally become effective with a spatial offset. That corresponds to a dead time under a control technical aspect. In disadvantageous cases oscillations (waviness) may occur. The offset corresponds to $\Delta x = v_x \cdot t_R$

and is therefore absolutely included in the range of the observed accuracies (e.g. $v_x = 01 \text{ m/s}$, $t_R = 0,5 \text{ ms}$, $\Delta x = 50 \mu\text{m}$). To compensate such disadvantageous effects it may be desirable to store measured values for the depth z and to take them into consideration later. This may lead to control overlapping or underlying the automatic control depending on the stored depth data.

Please replace the paragraph beginning at page 10, line 4, with the following rewritten paragraph:

The topographic mapping described may advantageously be combined with the determination of the substance removal boundaries in the horizontal direction described with reference to FIG. 4. Said techniques may be used in connection with the described measuring arrangement (referencing a calibrating curve) individually or in combination. The topographic mapping method described with reference to FIG. 5 can also be used together with the method for adjusting the relative position described in the other application ~~no. ...~~ ("Patching") U.S. Serial No. 09/806,353 of the applicant. For example, the relative positions of the working head and the workpiece may be selected so that critical areas on the workpiece (for example a plateau 103 or an indentation) will not come to be located in the boundary sections of the working area of the device so that a reliable processing of the corresponding position will become possible. ~~An influence on the~~

~~separation means supply in accordance with the application no. ... ("Trennmittel")~~
~~depending on the data stored during the topographic mapping is also possible.~~